

Sheet 1 of 2

FORM PTO-1449

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)

823.0052USQ1

Application Number

09/836,449

Applicant

Fonash et al.

Filing Date

April 17, 2001

Group Art Unit

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U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
RB	6,288,390	9/11/01	Siuzdak et al.	250	288	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

RB	Kim et al. "Thin-Film Micromirror Array." <i>Information Display</i> 4 & 5/99, 30-33.
	Yonehara et al. "ELTRAN; SOI-Epi Wafer by Epitaxial Layer Transfer from Pouous Si." ELTRAN Business Center, Canon, Inc., Abstract No. 438.
	Stern et al. "Nanochannel fabrication for chemical sensors." <i>J. Vac. Sci. Technol.</i> 15(6), Nov/Dec 1997, 2887-2891.
	Turner et al. "Monolithic Fabrication of Nanofluidic Artificial Gel Media for DNA Electrophoresis." <i>SPIE</i> Vol. 3258, 114-121.
	French. "Development of surface micromachining techniques compatible with on-chip electronics." <i>J. Micromech. Microeng.</i> (1996) 197-211.
	Sugiyama et al. "Micromachined sensors using polysilicon sacrificial layer etching technology." <i>IEDM Tech. Dig.</i> , (1994) 127-130.
	Bell et al. "Porous silicon as a sacrificial material." <i>J. Micromech. Microeng.</i> 6 (1996) 361-369.
	Steiner et al. "Using porous silicon as a sacrificial layer." <i>J. Micromech. Microeng.</i> 3 (1993) 32-36.
	Boer et al. "Micromachining of buried micro channels in silicon." <i>J. Micromech. Systems</i> , Vol. 9, No. 1, March 2000, 94-103.
RB	Uhlir, Jr. "Electrolytic shaping of Germanium and Silicon." <i>The Bell System Technical Journal</i> . March 1956. 333-347.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609; Draw line through

citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

